APPLICATION DATA SHEET

Electronic Version 0.0.11

Stylesheet Version: 1.0

Attorney Docket Number: 8289-US-PA

Publication Filing Type:

new-utility

Application Type:

utility

Title of Invention:

WAFER LEVEL PACKAGING AND CHIP STRUCTURE

Customer Number Attorney:

31561

Customer Number Correspondence Address:

31561

Foreign Priority:

90132737

ا الم

TW 2001-12-28

Priority Claimed

INVENTOR(s):

Primary Citizenship:

TAIWAN

Given Name:

Chi-Hsing

Family Name:

Hsu

Residence City:

Taipei Hsien

Residence Country:

TW

Address:

9F-1, No. 23, Changlung St., Hsinchuang

Taipei Hsien, TW